

# SOT1962-1

LFBGA485, plastic, low profile fine-pitch ball grid array package; 485 balls; 0.5 mm pitch; 14 mm x 14 mm x 1.25 mm body

24 January 2018

Package information

## 1. Package summary

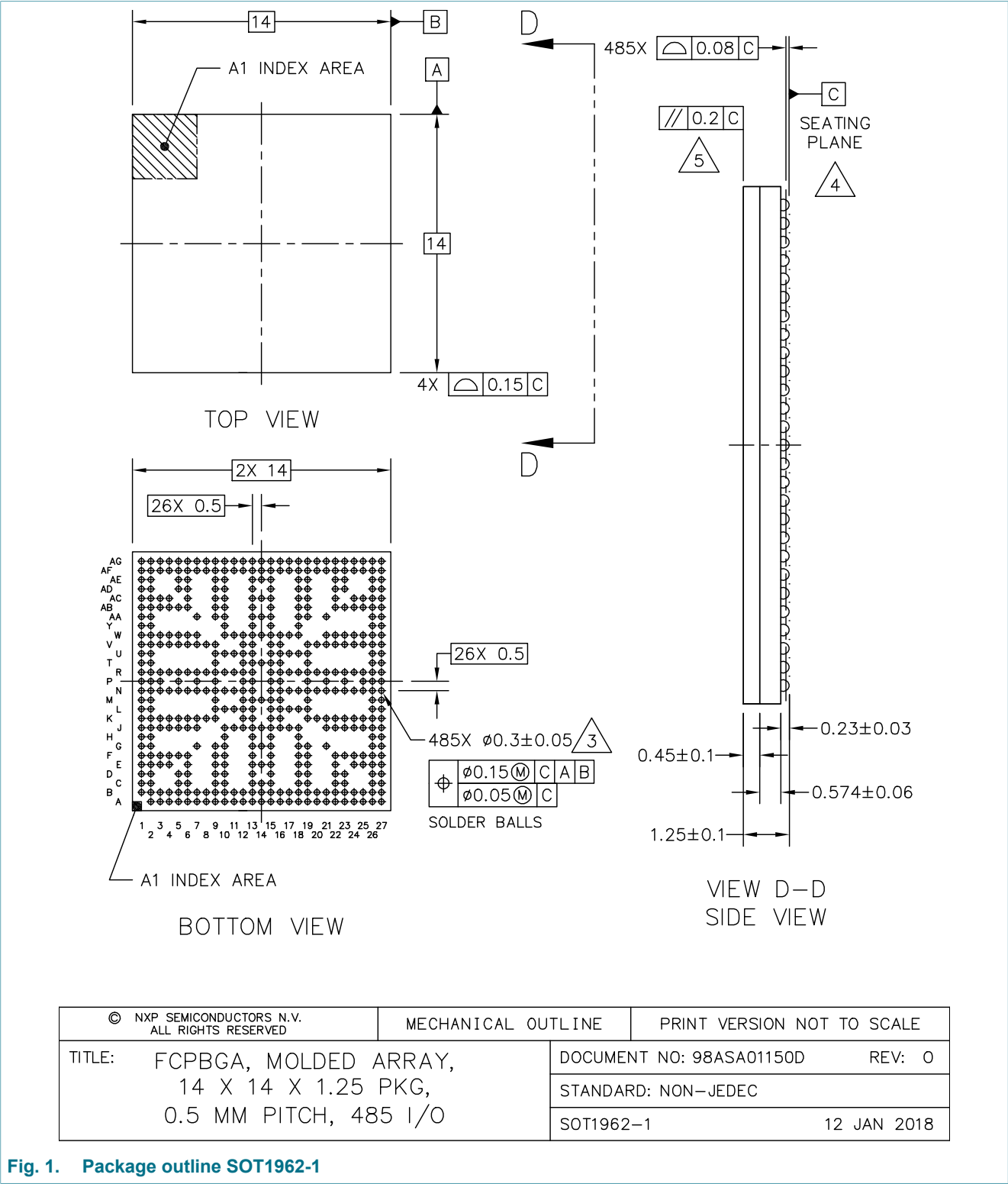
Terminal position code	B (bottom)
Package type descriptive code	LFBGA485
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-1-2018
Manufacturer package code	98ASA01150D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	14	-	mm
E	package width		-	-	14	-	mm
A <sub>2</sub>	package height		-	-	1.25	-	mm
e	nominal pitch		-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	485	-	A/A



2. Package outline



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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- 6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: FCPBGA, MOLDED ARRAY, 14 X 14 X 1.25 PKG, 0.5 MM PITCH, 485 I/O	DOCUMENT NO: 98ASA01150D	REV: 0
	STANDARD: NON–JEDEC	
	SOT1962–1	12 JAN 2018

Fig. 2. Package outline note LFBGA485 (SOT1962-1)

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### 3. Legal information

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